Product Change Notification: BLAS-01LYLU604

Date:

10-Sep-2025

Product Category:

32-Bit Microcontrollers

Notification Subject:

CCB 7564.001 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected ATSAMD20E14, ATSAMC20E15A, ATSAMC20E16A, ATSAMC20E17A, ATSAMC20E18A, ATSAMC21E15A, ATSAMC21E16A, ATSAMC21E17A, ATSAMC21E18A, ATSAMD20E15, ATSAMD20E16, ATSAMD20E17, ATSAMD20E18, ATSAMD21E15, ATSAMD21E15L, ATSAMD21E16, ATSAMD21E16L, ATSAMD21E17, ATSAMD21E17L, ATSAMD21E18, ATSAML10E14A, ATSAML10E15A, ATSAML10E16A, ATSAML11E14A, ATSAML11E15A and ATSAML11E16A device families available in 32L VQFN (5x5x1mm) package.

Affected CPNs:

BLAS-01LYLU604_Affected_CPN_09102025.pdf
BLAS-01LYLU604_Affected_CPN_09102025.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected ATSAMD20E14, ATSAMC20E15A, ATSAMC20E16A, ATSAMC20E17A, ATSAMC20E18A, ATSAMC21E15A, ATSAMC21E16A, ATSAMC21E17A, ATSAMC21E18A, ATSAMD20E15, ATSAMD20E16, ATSAMD20E17, ATSAMD20E18, ATSAMD21E15, ATSAMD21E15L, ATSAMD21E16, ATSAMD21E16L, ATSAMD21E17, ATSAMD21E17L, ATSAMD21E18, ATSAML10E14A, ATSAML10E15A, ATSAML10E16A, ATSAML11E14A, ATSAML11E15A and ATSAML11E16A device families available in 32L VQFN (5x5x1mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change
Assembly Site	Microchip Technology Inc. (MPHIL-3) (MP3A)	Microchip Technology Inc. (MPHIL-3) (MP3A)
Wire Material	Au	CuPdAu
Die Attach Material	3280	3280NP
Molding Compound Material	G700LTD	G700LTD
Lead-Frame Material	C194	C194

*3280NP is a non-PFAS die attach material

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: September 2025

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	September 2025				
Work Week	36	37	38	39	40
Initial PCN Issue Date	x				
Qual Report Availability					x
Final PCN Issue Date					x

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: September 10, 2025: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_BLAS-01LYLU604_Qualification_Plan_.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.